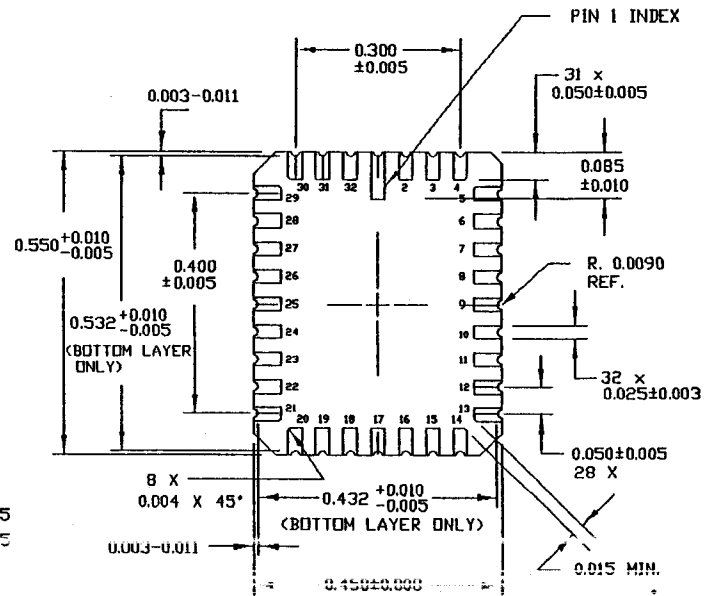
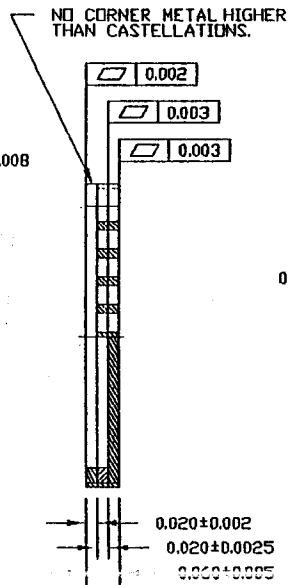
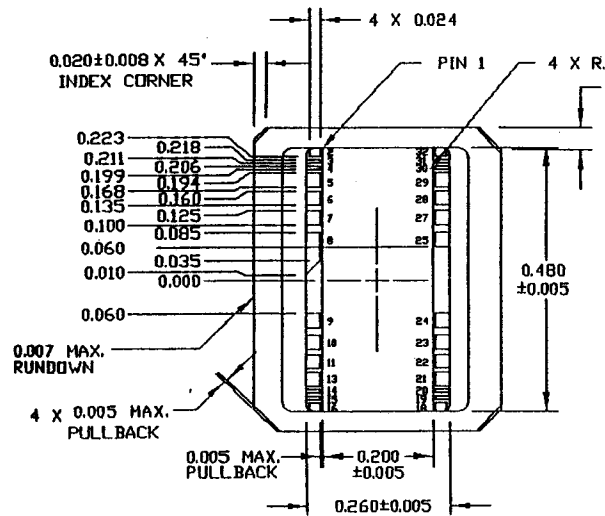


# SSM P/N LCC03256

- NOTES:
1. INTERPRET DRAWING PER DOD-STD-100.
  2. DIMENSIONS ARE TYPICAL FOR ALL QUADRANTS UNLESS OTHERWISE SPECIFIED.
  3. BOND FINGERS AND SEAL RING WILL BE PLATED WITH GOLD (80 μ IN. MIN.) OVER NICKEL (80 μ IN. MIN.). DIE ATTACH CAVITY WILL HAVE NO METALIZATION.
  4. DIE ATTACH CAVITY AND SEAL RING WILL BE ELECTRICALLY ISOLATED.
  5. LEADS 1, 12, 17 AND 26 ARE NOT CONNECTED TO INTERNAL BOND PADS.
  6. ALL PARTS SHALL CONFORM TO CYPRESS SEMICONDUCTOR SPECIFICATION NO. 03-00027.
  7. PARTS SHALL COMPLY TO C-12A CONFIGURATION ON MIL-STD-1835.



|                              |           |             |          |                           |          |              |     |
|------------------------------|-----------|-------------|----------|---------------------------|----------|--------------|-----|
| UNLESS OTHERWISE SPECIFIED   |           | DESIGNED BY | DATE     |                           |          |              |     |
| ALL DIMENSIONS ARE IN INCHES |           | HTN         | 07/01/93 |                           |          |              |     |
| STANDARD TOLERANCES ON       |           | CHK BY      | DATE     |                           |          |              |     |
| DECIMALS                     | ANGLES    | BSC         | DATE     |                           |          |              |     |
| JXX ± 0.003                  |           |             |          | TITLE 32 LD LCC 200 X 480 |          |              |     |
| JXXX ± 0.0010                |           |             |          | SIZE                      | PART NO. | DWG NO.      | REV |
| MATERIAL                     | SEE NOTES | APPROVED BY | DATE     | B                         |          | 51-20245     | **  |
| FINISH                       | SEE NOTES |             |          | SCALE 5:1                 |          | SHEET 1 OF 1 |     |

